



Title of Change:	UNIFET FAB process optimized to improve HTRB Performance by adding Blanket IMP process.				
Proposed first ship date:	6 November 2018 or earlier upon customer approval				
Contact information:	Contact your local ON Semiconductor Sales Office or <Sungdae.shin@onsemi.com>				
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.				
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Byeongyeop.Lee@onsemi.com>				
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>				
Change Part Identification:	Affected products will be identified with date code.				
Change Category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____				
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input checked="" type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____				
Sites Affected:	ON Semiconductor Sites: ON Suzhou, China		External Foundry/Subcon Sites: None		
Description and Purpose: UNIFET FAB process optimized to improve HTRB Performance by adding Blanket IMP process. There are no product material changes as a result of this change. There is no product marking change as a result of this change.					
Reliability Data Summary: QV DEVICE NAME: FSB50550US / FSB50550A RMS: K45104 PACKAGE: SPM5 ver 1.5 / SPM5 ver 2.0					
Test	Specification	Condition	Interval	Results Ver 1.5	Result Ver 2.0
HTRB	JESD22-A108	150°C for 1008 hours, Vds=400V, Vcc=20V, Vin=0V	1,008 hrs	0/11	0/11
TC	JESD22-A104	Ta= -40°C to +125°C	1,000 cyc	0/11	0/11
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/11	0/11

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted

List of Affected Parts:

Part Number	Qualification Vehicle
NBC9620	FSB50550A
NBC9619	FSB50550A
NBC9616	FSB50550US
NBC9615	FSB50550US
FSB50550UTD	FSB50550US
FSB50550US	FSB50550US
FSB50550TB2	FSB50550US
FSB50550AT	FSB50550A
FSB50550ASE	FSB50550A
FSB50550AS	FSB50550A
FSB50550ADL	FSB50550A
FSB50550AD	FSB50550A
FSB50550AB	FSB50550A
FSB50550A	FSB50550A
FSB50450US	FSB50550US
FSB50450UD	FSB50550US
FSB50450AT	FSB50550A
FSB50450AS	FSB50550A
FSB50450A	FSB50550A
FSB50350ATF	FSB50550A
FSB50350ASF	FSB50550A
FSB50250UTD	FSB50550US
FSB50250US	FSB50550US
FSB50250UD	FSB50550US
FSB50250AT	FSB50550A
FSB50250AS	FSB50550A
FSB50250AP	FSB50550A
FSB50250AB	FSB50550A
FSB50250A	FSB50550A